

List of Publications

R. Dekker, R. van Es, S. Jansen, P. Kranen, H. Maas, A. Pruijmboom and J. van der Velden, "Charge sharing effects in bipolar transistors with sub-halfmicron emitter widths," in *IEEE Int. Electron Devices Meeting (IEDM) Tech. Dig.*, 1990, pp. 29-32

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R. Dekker, "Ultra-thin flexible silicon circuits for RF-ID," tutorial for *11th European Workshop on Thin Silicon Devices*, Delft 2-4 February, 2005

R. Dekker, M. Dümling, J.-H. Fock, O. Gourhant, R. Kubrin, T.M. Michielsen, H. Pohlmann, W. Schnitt, A.M.H. Tombeur and T. Zoumpoulidis, "CIRCONFLEX: an ultra-thin and flexible technology for RF-ID tags," in *Proc. 15th European Microelectronics and Packaging Conference & Exhibition (IMAPS)*, June 12-15, Brugge Belgium, 2005, pp. 268-271

R. Dekker, M. Dümling, J.-H. Fock, O. Gourhant, C. Jonvill, T.M. Michielsen, H. Pohlmann, W. Schnitt, A.M.H. Tombeur and T. Zoumpoulidis, "A 10 μm Thick RF-ID Tag for Chip-in-Paper Applications," in *Proc. IEEE Bipolar/BiCMOS Circuits and Technology meeting (BCTM)*, 2005, pp. 18-21

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